



Advanced Polymer Materials for Stretchable Electronics

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Message from the Guest Editor

Electronic skins are emerging technologies that based on stretchable electronics and related integrated circuits. They have great potential in a broad range of applications such as prosthetics, artificial intelligence, soft robotics and health monitoring. In the development of stretchable electronics, polymeric materials have played important roles due to their intrinsic flexibility, which can help devices to dissipate externally applied strain, and maintain the performance during deformation. Moreover, their electrical and mechanical properties, which are critical to stretchable electronics, could be further improved through chemical modification or physical blend. The advancement of polymers can promote the fields, evolve the stretchable devices, make electronic skin more like human skin. Accordingly, this Special Issue seeks to showcase research papers, communications, and review articles that focus on polymeric materials used in stretchable electronics.





Editor-in-Chief

Message from the Editor-in-Chief

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